No	Module name		Status	Remark
General Configuration				
1	Process		HTO	
2	Model		DJ-833V	1996 / 7
3	Wafer Size		200mm	
4	Process Wafer Qty		100pc	
5	Process Type		LP-CVD	
6	I/O Port or Smif		I/O Port	
7	Gas Supply		U-Box Lower	
8	PCW Supply		U-Box Lower	
9	Carrier Slot		25 Slot	
10	Load Lock System		NA	
11	Rcu Unit System		NA	
12	Quartzware(1set)		NA	
System Control				
1	Main Controller		CX3001A	
2	Sequencer		CX1314	
3	Operation Screen		CX3001P	F, R
4	Gas Flow Chart		Yes	
5	Temperature Controller		CQ1500A	
6	Over Temp Controller		DN-130L	
7	Pressure Control		Yes	MFCP
8	Tape Heater Controller		NA	
9	Control Power		100V	
10	Pump Unit		NA	
Process Gasses				
1	Process Gas 1		N2	
2	Process Gas 2		SiH4	
3	Process Gas 3		N2O	
4	Process Gas 4		SiH2Cl2	
Gas Distrubution System				
1	Basic Style		Auto Weld	
2	Tubing Matrial		SUS-316L	
3	Tubing Finish		VCR	
4	MFC		STEC	
Exhaust Distribution System				
1	Pirani Controller		Yes	
2	Baratron Gauge		Yes	
3	Main Valve		Yes	
4	Heating Jacket		NA	
5	Cold Trap		NA	
6	Pump Line		Yes	
Wafer/Cassette Handling				
1	Wafer Alignment		Flatzone	
2	Cassette Storage Qty		16ea	
3	Cassette In/Out Port		Yes	
4	Cassette Handling Robot		Yes	
5	Wafer Transfer Type		Vacuum Type	
6	Fork Matrial		Quartz	
7	Fork Qty		5pc	
8	Fork Variable Pitch		Yes	
9	Fork Wafer Presence Sensor		Yes	
Elevator Handling				
1	Boat Elevator		Yes	
2	Auto Shutter		Yes	
3	Boat Rotation		NA	
4	Mechanical Parts		Yes	
電源系	POWER	Controller	1 ϕ 100V(3KVA)	
		Heater	3 ϕ 200V(54KVA)	
Other	裝置大小		900x1950x2800	
	UTILITY BOX大小		900x900x2800	
	Main Body與Utility box間距大小		1000	